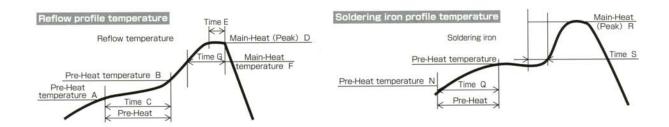
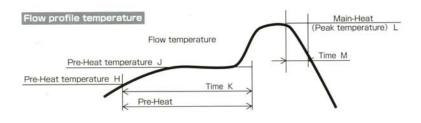
REFIOW PROFILE





	. devices type	Mount division	Reflow/Flow solder temperature								
			Reflow								
No.			Pre-Heat temperature			Main-Heat temperature				Frequency	
			temperature °C A	temperature °C B	time ≦sec C	peak °C Max. D	time ≦sec E	temperature ≧°C F	time ≦sec G	(time)	
1	ceramic arrester (2P)	insertion	150	200	30	260	10	240	10	2	
2	ceramic arrester (3P)	insertion	150	200	30	260	10	240	10	2	
3	3P with FS type	insertion	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	

		Mount division	Reflow/Flow solder temperature							
No.	devices type		Pre-Heat			Main-Heat		Frequency		
			temperature °C H	temperature ℃ J	time ≦sec K	peak "C Max. L	time ≦sec M	(time)		
1	ceramic arrester (2P)	insertion	150	200	30	260	10	2		
2	ceramic arrester (3P)	insertion	150	200	30	260	10	2		
3	3P with FS type	insertion	150	200	30	260	10	2		

	devices type	Mount division	Soldering iron profile temperature							
			Temp of solder iron							
No.			Pre-Heat			Main-Heat		2000		
			temperature °C N	temperature °C P	time ≦sec Q	peak °C Max. R	time ≦sec S	Note		
1	ceramic arrester (2P)	insertion	150	200	30	350	3			
2	ceramic arrester (3P)	insertion	150	200	30	350	3			
3	3P with FS type	insertion	150	200	30	350	3			